

Item no.: 345040

## APU3D4 - System board, 4 GB, 3x Intel GigE, optimized for LTE, Intel i211 NIC

## from 178,71 EUR

shipping weight: 0.30 kg Manufacturer: PC Engines



## Product Description

PC Engines APU3D4 - System board, 4 GB, 3x Intel GigE, optimized for LTE

This board version is targeted at applications that require 2x 3G/LTE modems. SIM sockets can be swapped under GPIO control, enabling failover between two different networks even when only one modem is used. Another feature is the build option for a regular PCI express slot on the side. APU3D updates

- Changed battery socket footprint to avoid contact problems.

- Improved power regulator stability.
  Added optional 10-pin LPC header to support tpm4a module.
  Added W\_DIS# series resistor to support Quectel EP06 modules.
  Some changes to avoid leakage between V3 and V3A power rails.
  Added signal integrity resistor for core voltage control signal.

- CPU: AMD Embedded G series GX-412TC, 1 GHz quad Jaguar core with 64-bit and AES-NI support, 32K data + 32K instruction cache per core, shared 2 MB L2 cache DRAM: 4 GB DDR3-1333 DRAM Storage: Boot from SD card (internal sdhci controller), external USB or m-SATA SSD, 1x SATA + power connector, mSATA is shared with miniPCI express

- 12 V DC, about 6 to 12 W depending on CPU load, jack = 2.5 mm, center positive
  Connectivity: 3x Gigabit Ethernet channels (Intel i211 NIC)
  I/O: DB9 serial port, 2x USB 3.0 external + 4x USB 2.0 internal, 3x front panel LEDs, pushbutton
- Expansion: 3x miniPCI express (J14 USB or mSATA, with SIM; J15 USB only, with SIM; J16: full miniPCI express, but no SIM, intended for Wi-Fi), GPIO header, optional I2C bus, COM2 (3.3 V RXD/TXD)
- Board size: 6 x 6 inch (152.4 x 152.4 mm) same as apu1d, alix2d13 and wrap1e
- Cooling: Conductive cooling from the CPU to the enclosure using a 3 mm alu heat spreader (included)

## Specifications

Scan this QR code to view the product All details, up-to-date prices and availability

